

Fig. 1A

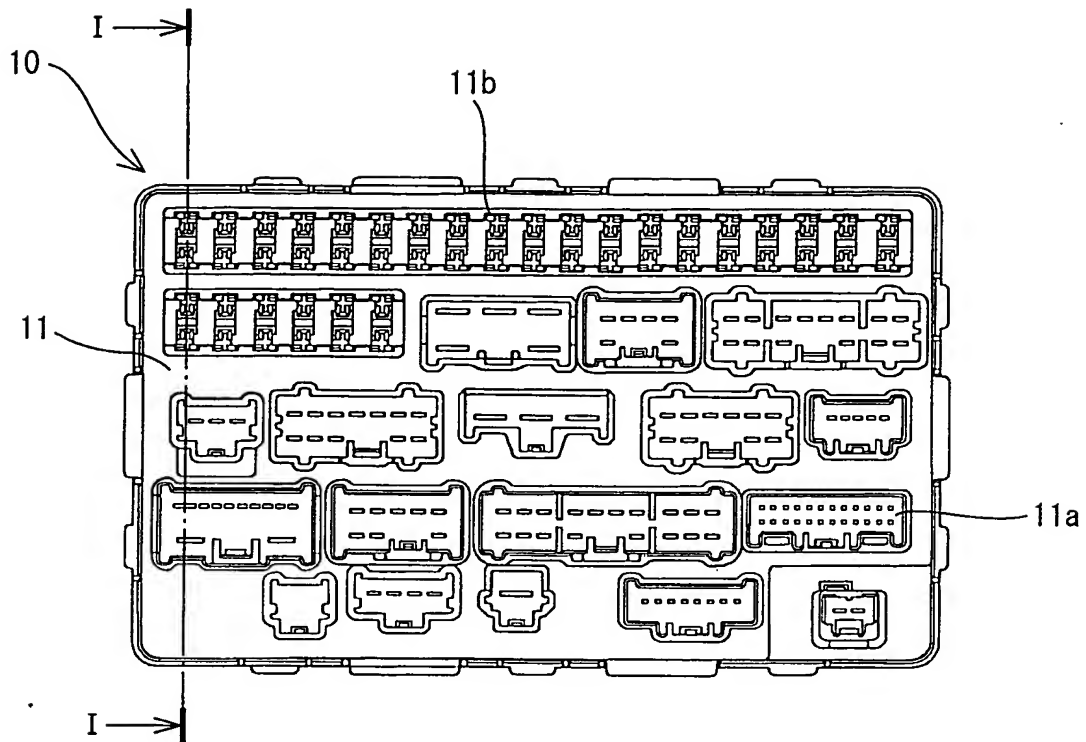


Fig. 1B

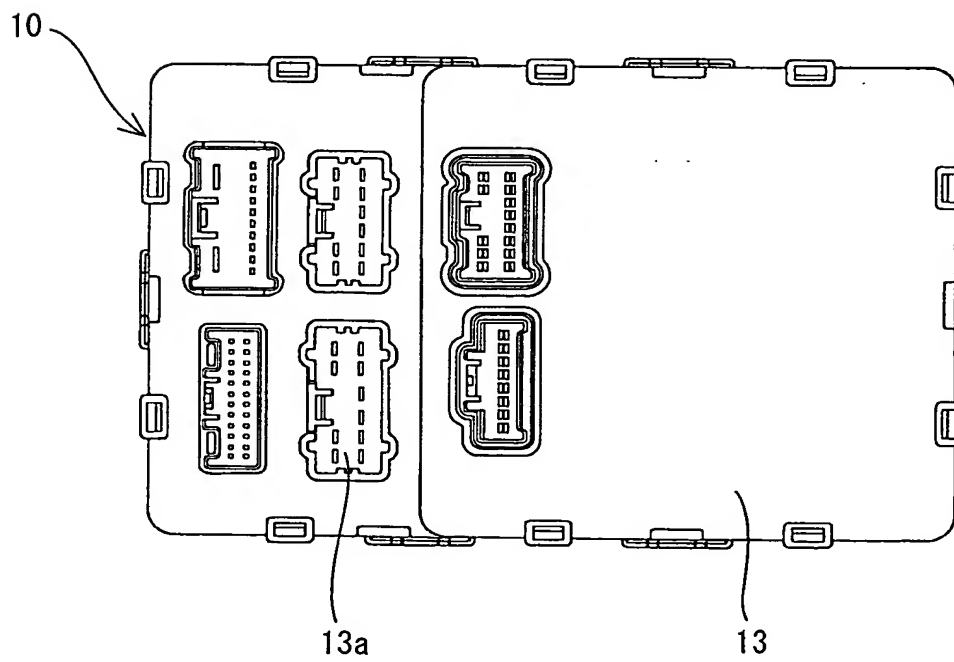


Fig. 2

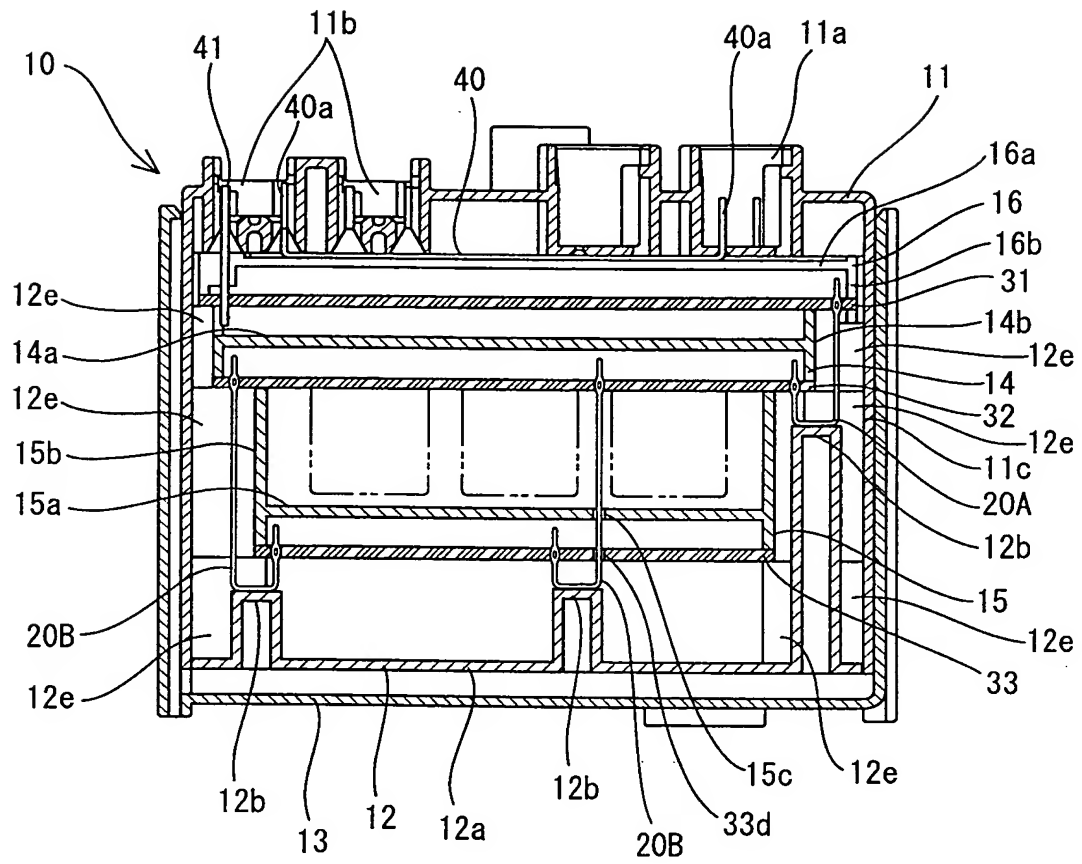


Fig. 3

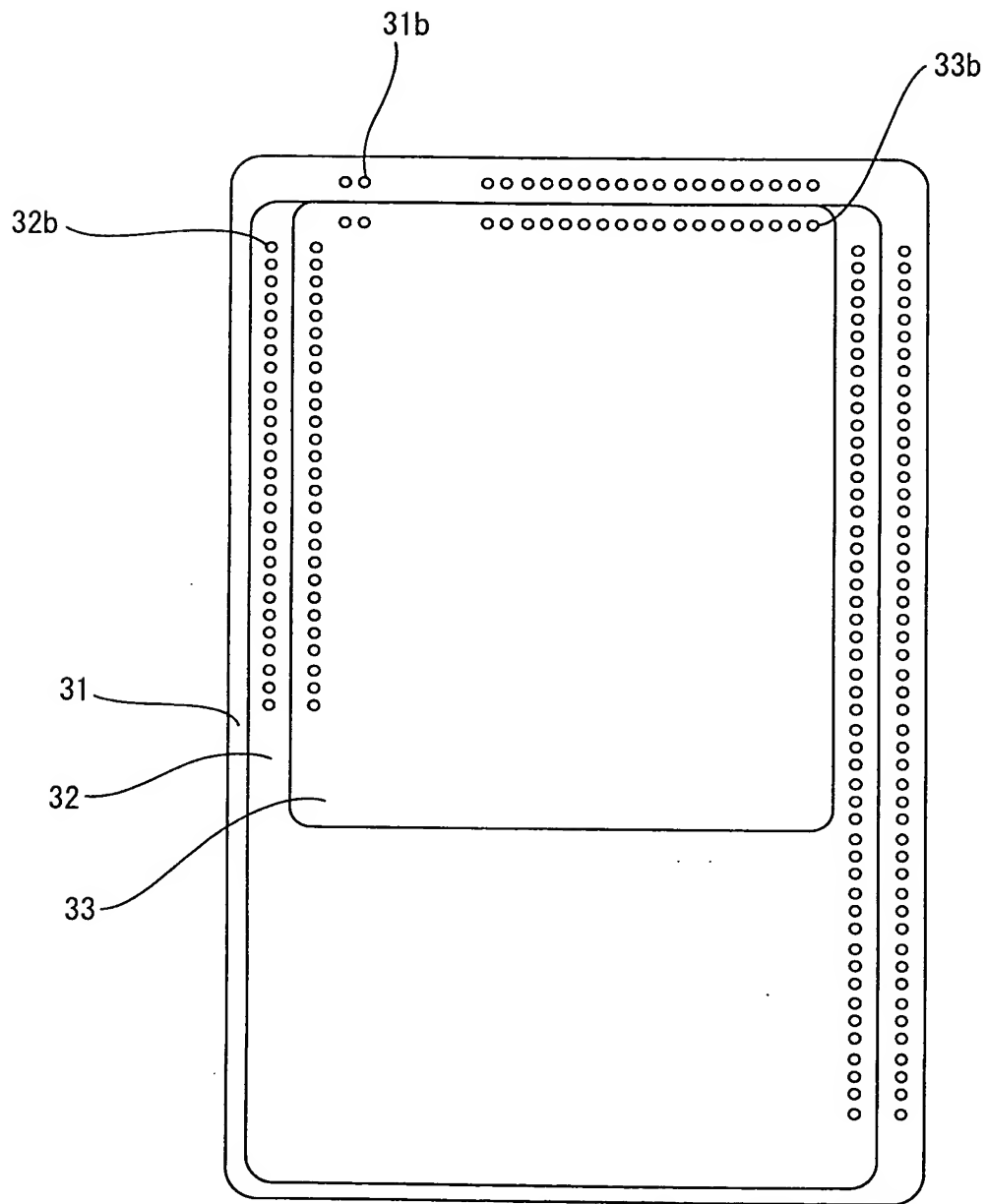


Fig. 4

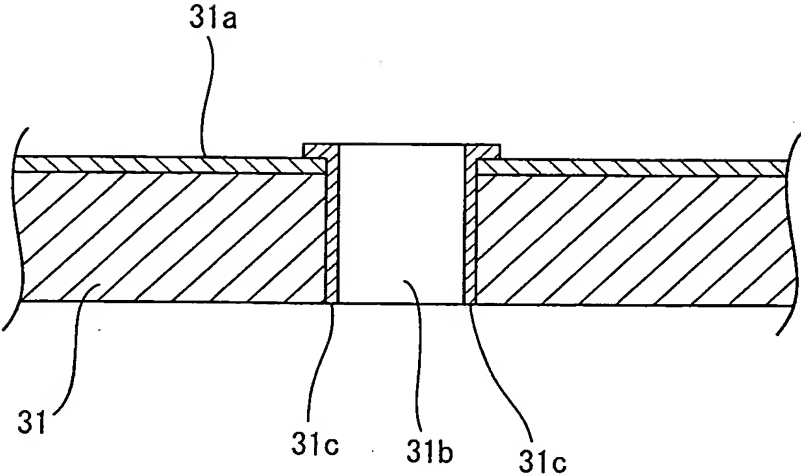


Fig. 5

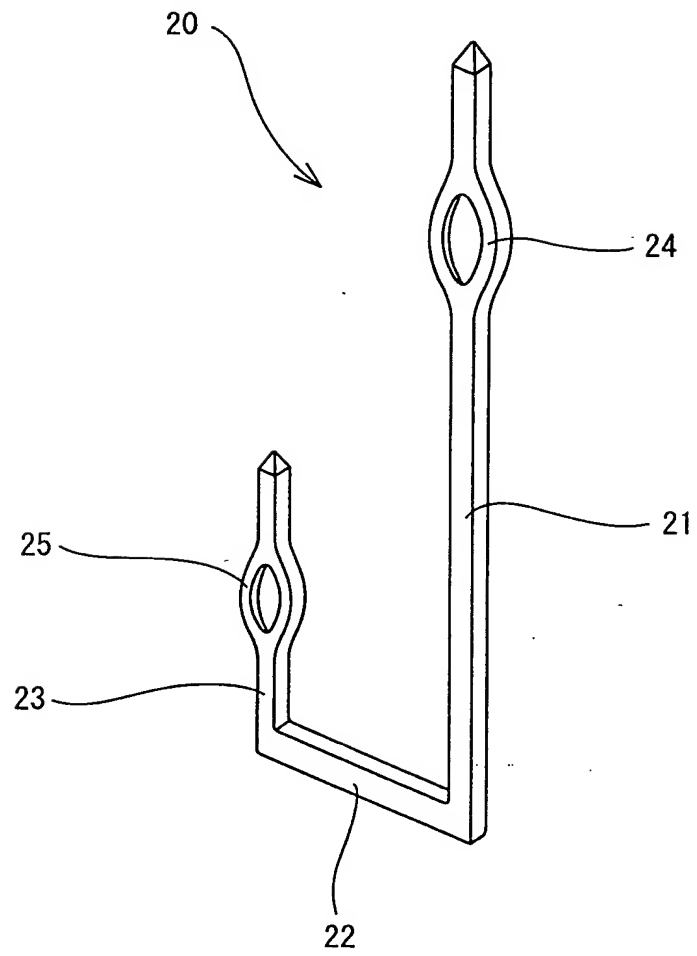


Fig. 6

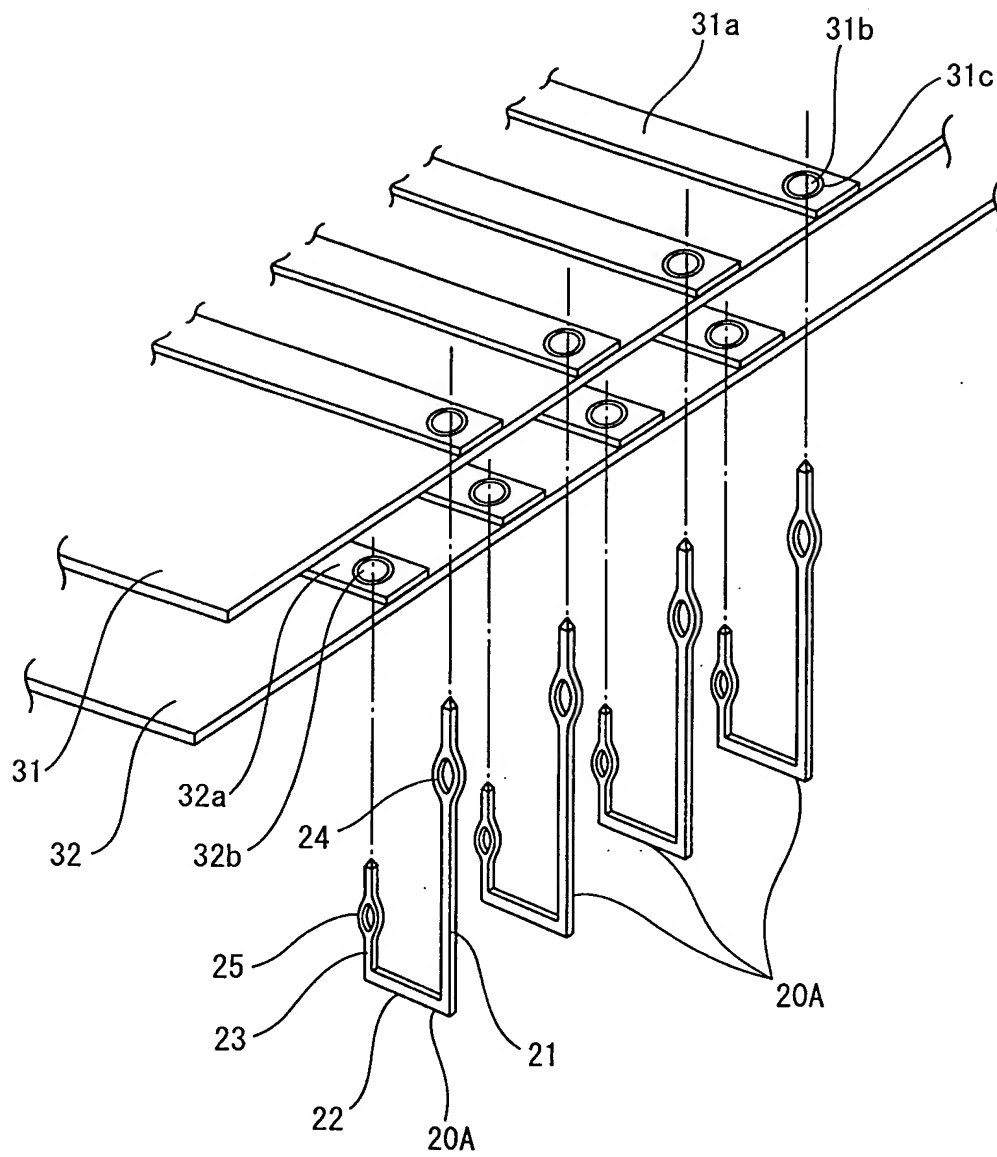


Fig. 7

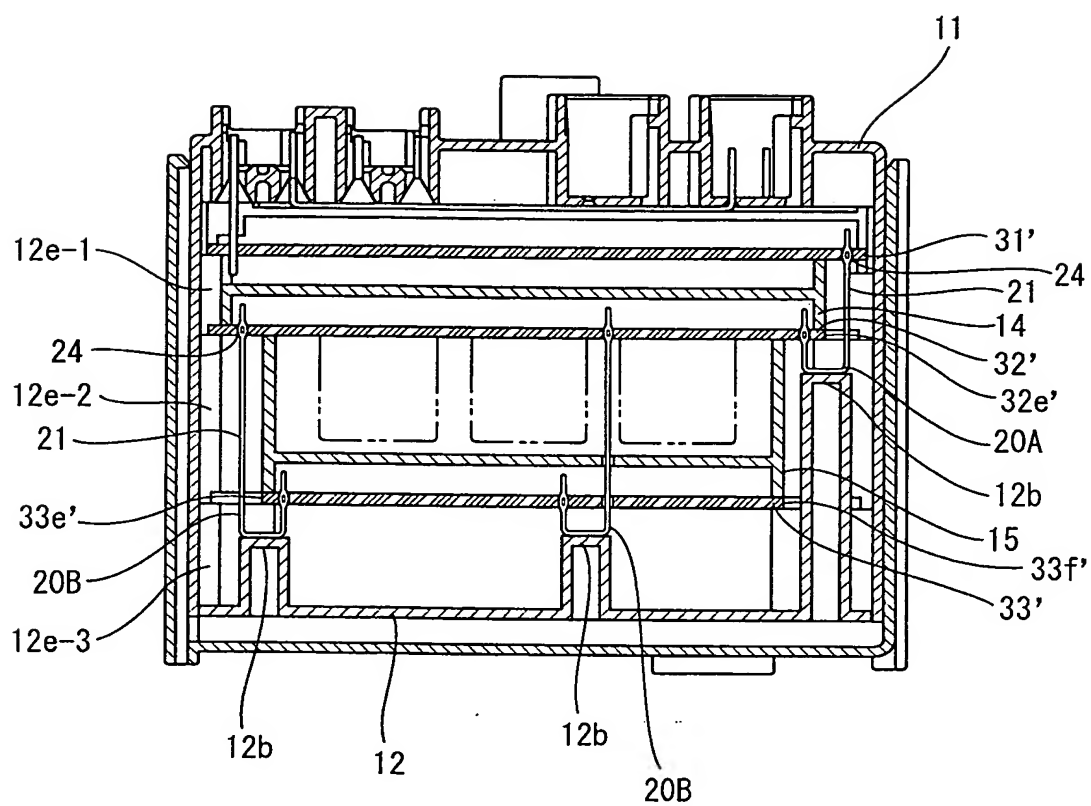


Fig. 8

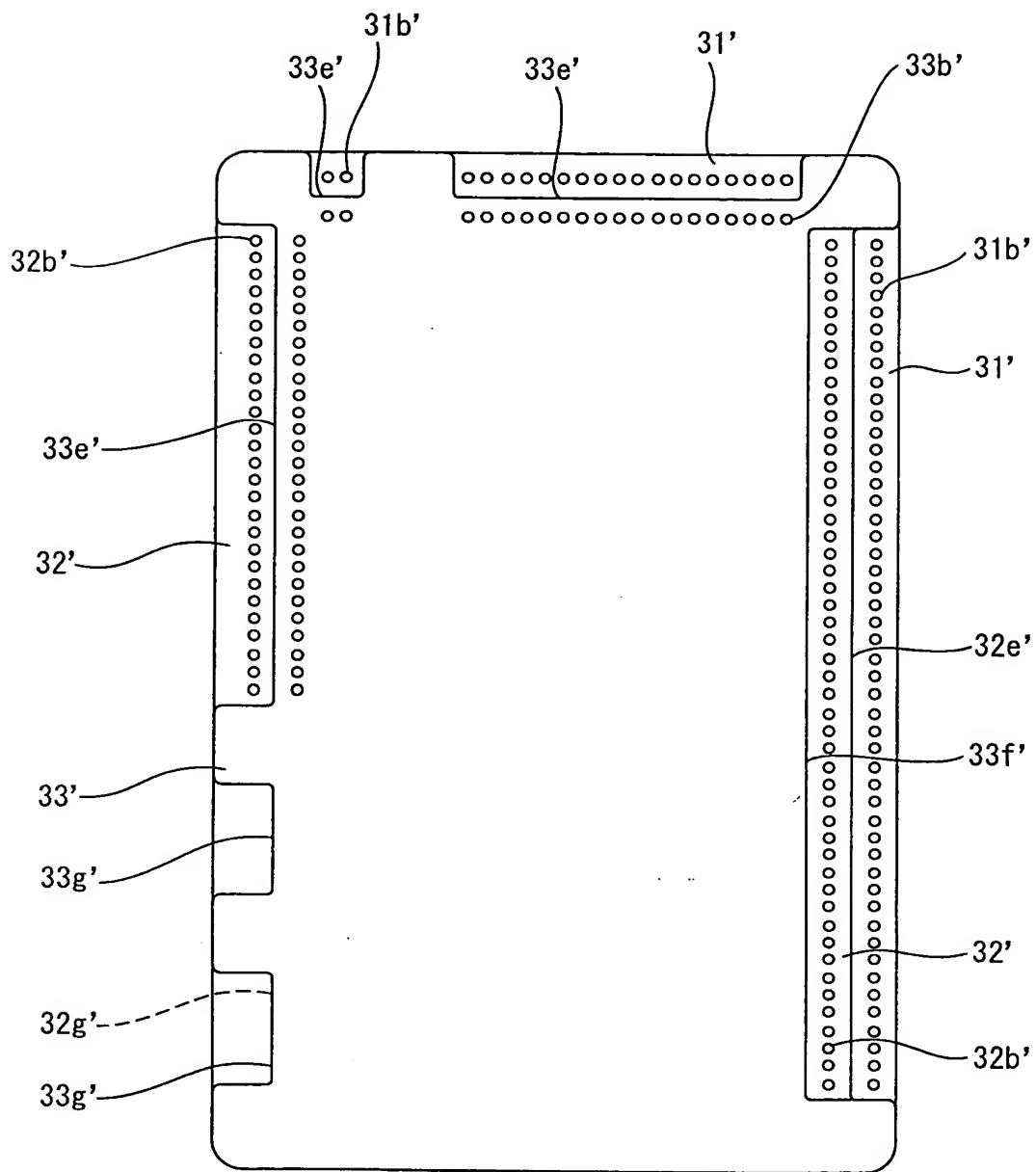




Fig. 9A

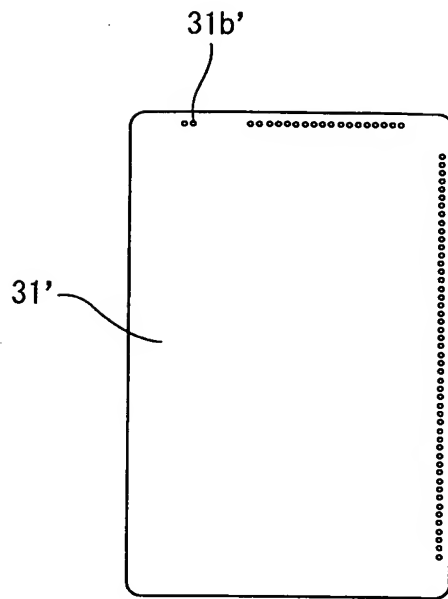


Fig. 9B

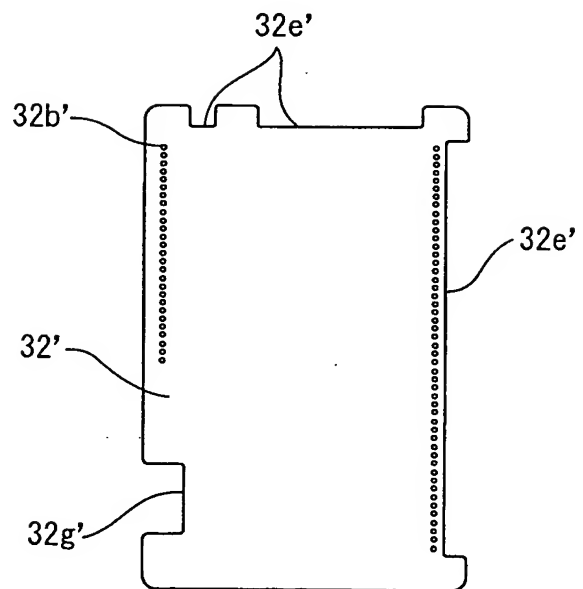
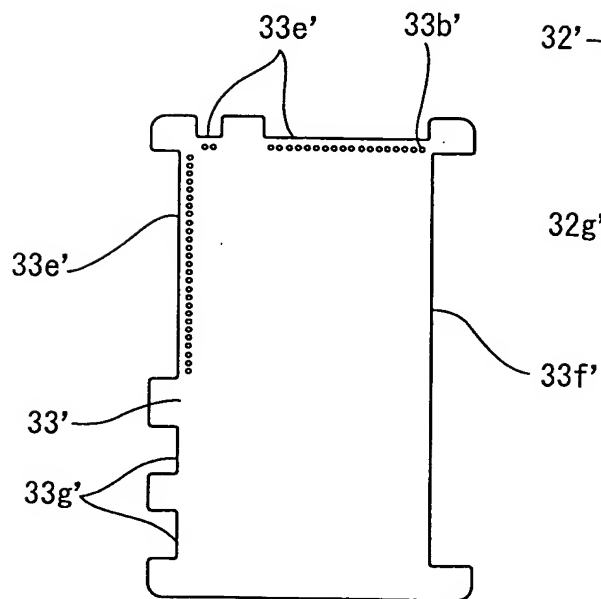


Fig. 9C



This diagram shows a cross-sectional view of a multi-layered electronic device assembly. The assembly consists of several stacked layers, including a top layer (10'), a middle layer (11'), and a bottom layer (12'). The layers are separated by spacers (20A, 20B) and connected by vertical vias (50a). The assembly is housed within a frame (12c') and includes various components such as a top cover (12d'), a bottom cover (12d'), and a central core (50). The diagram illustrates the internal structure and the connection between different layers and components.

Fig. 11

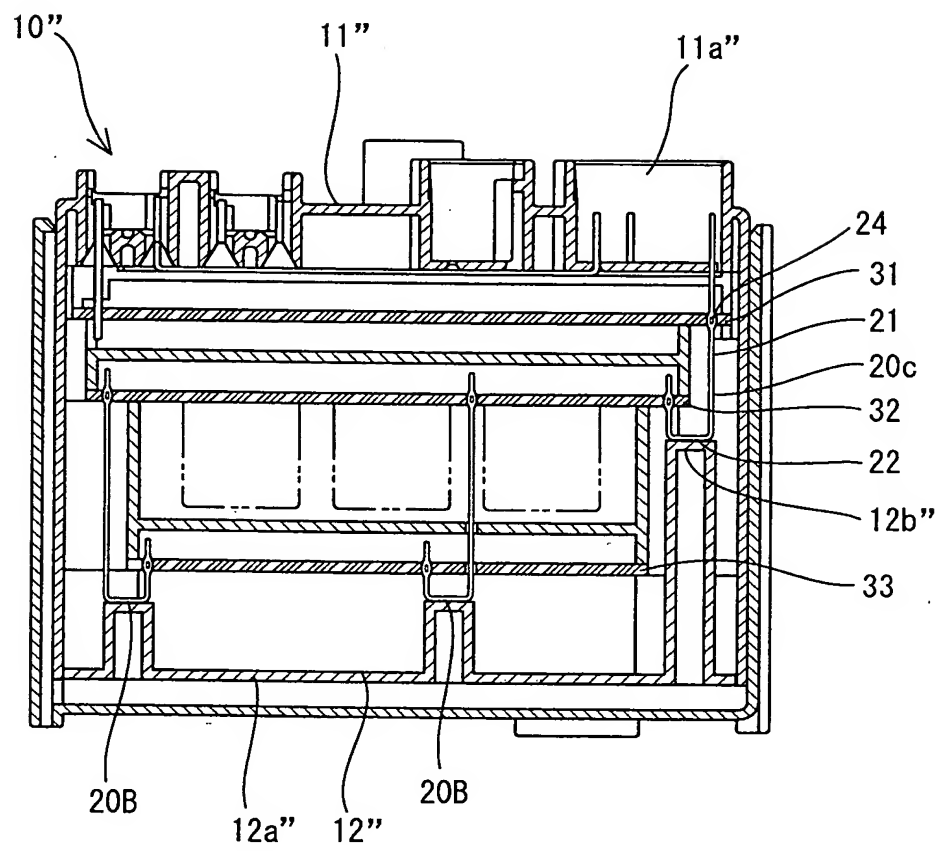


Fig. 12

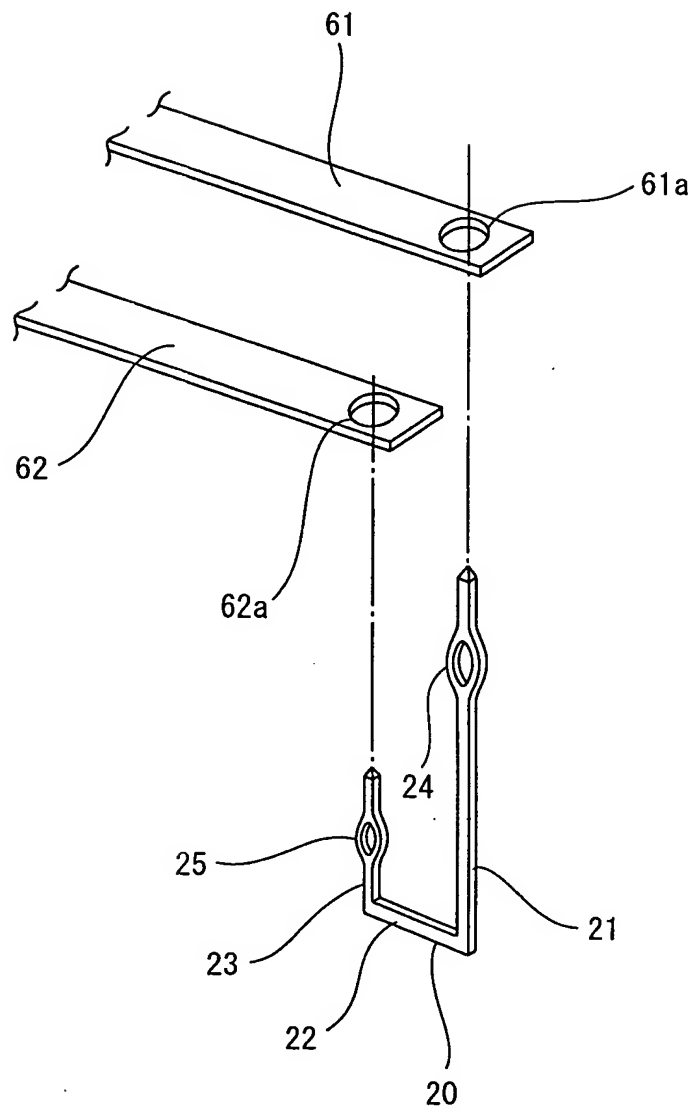
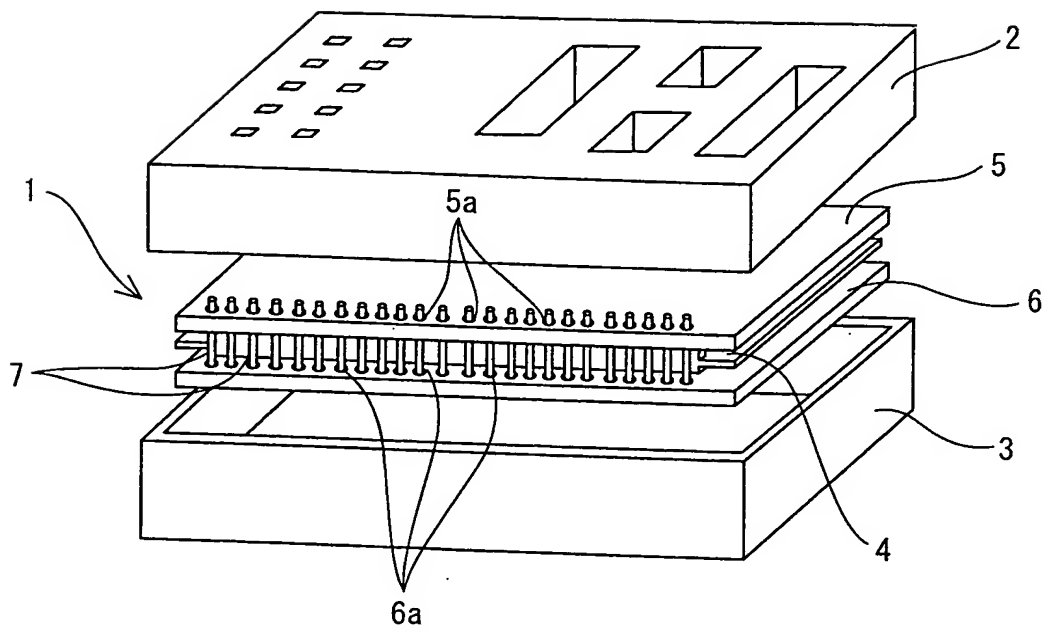


Fig. 13



[Prior Art]